T591 Series High Performance Automotive Grade Polymer Tantalum 105°C/125°C



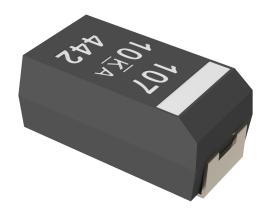
Overview

The KEMET Organic Capacitor is a tantalum capacitor with a Ta anode and ${\rm Ta}_2{\rm O}_5$ dielectric. A conductive organic polymer replaces the traditionally used MnO $_2$ as the cathode plate of the capacitor. This results in very low ESR and improved capacitance retention at high frequency. The polymer technology also exhibits a benign failure mode which eliminates the ignition failures that can occur in standard MnO $_2$ tantalum types. Polymer tantalum capacitors may be operated at voltages up to 90% of rated voltage for part types with rated voltages of \leq 10 volts with equivalent or better reliability than traditional MnO $_2$ tantalum capacitors operated at 50% of rated voltage.

The T591 Series High Performance Automotive Grade Polymer was developed to deliver higher stability under harsh conditions of humidity and temperature. Special enhancements in design and material setting was introduced in the build of the material to deliver 500 hours under 85°C / 85% RH/Ur. This T591 Series is manufactured in a ISO TS 16949 certified plant and is subject to PPAP/PSW and change control.

Benefits

- · Ultra-low ESR
- Polymer cathode technology
- · Non-ignition failure mode
- Operating temperature range of -55°C to 105°C / 125°C
- Complies with AEC–Q200
- High reliability up to 500 hours with 85°C / 85% RH load
- Capacitance up to 220 µF
- Voltage range of 2.5 10 V
- Capacitance tolerance of ±20%
- · Laser marked case
- · RoHS Compliant and lead-free terminations
- · Halogen-free epoxy
- TS 16949 certified plant
- Meets or exceeds EIA standard 535BAAC
- Taped and reeled per EIA 481



Applications

Typical applications include decoupling and filtering in a variety of market segments, with special emphasis in automotive applications such as: Infotainment and output in DC/DC converters where harsh conditions such high humidity and temperature are a concern.



Environmental Compliance

RoHS Compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder.



SPICE

For a detailed analysis of specific part numbers, please visit www.kemet.com for a free download of KEMET's SPICE software. The KEMET SPICE program is freeware intended to aid design engineers in analyzing the performance of these capacitors over frequency, temperature, ripple, and DC bias conditions.

Ordering Information

Т	591	D	107	M	010	Α	Т	E025
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Failure Rate/ Design	Lead Material	ESR
T = Tantalum	591 = Automotive Grade Polymer	B, D, V	First two digits represent significant figures. Third digit specifies number of zeros.	M = ±20%	2R5 = 2.5 V 006 = 6.3 V 010 = 10 V	A = N/A	T = 100% Tin (Sn)	Maximum ESR in mΩ, 025 = 25 mΩ

Performance Characteristics

Item	Performance Characteristics
Operating Temperature	-55°C to 105°C / 125°C
Rated Capacitance Range	33 – 220 μF @ 120 Hz/25°C
Capacitance Tolerance	M Tolerance (20%)
Rated Voltage Range	2.5 – 10 V
DF (120 Hz)	Refer to Part Number Electrical Specification Table
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	≤ 0.1 CV (µA) at rated voltage after 5 minutes



Qualification

Test	Condition			Charac	cteristics			
			Δ C/C	Within -20%	%/+10% of initi	al value		
Freduces	105°C @ rated voltage, 2,000 hours**		DF	Within 2 x I	nitial Limits			
Endurance	125°C @ 2/3 rated voltage, 1,000 hours**	DCL	Within 2 x Initial Limit					
		ESR	Within 2 x I	nitial Limit				
			Δ C/C	∆ C/C Within -20%/+10% of initial va				
Storage Life	105°C @ 0 volts, 2,000 hours**		DF	Within 2 x I	nitial Limits			
	125°C @ 0 volts, 1,000 hours		DCL	Within 2 x I	nitial Limit			
		ESR	Within 2 x I	nitial Limit				
		Δ C/C	Within -5%	/+35% of initia	ıl value			
11	Humidity 85°C, 85% RH, Load, 500 hours				Initial Limits			
Humidity	85 C, 85% RH, Load, 500 nours		DCL	Within Initial Limit				
			ESR	Within 2 x I	nitial Limit			
			Δ C/C	Within -20%	%/+10% of initi	al value		
Thermal Shock	MIL-STD-202, Method 107, Condition B, mounte	DF	Within Initia	al Limits				
i nermai Snock	-55C° to 105°C / 125°C, 1,000 cycles	DCL	Within Initial Limit					
			ESR	Within 2 x Initial Limits				
			Δ C/C	Within -20%	%/+10% of initi	al value		
Curre Veltare	105°C, 1.32 x rated voltage, 1,000 cycles, 33 Ω	in series	DF	Within initia	Il limits			
Surge Voltage	125°C, 1.32 x rated voltage, 1,000 cycles, 33 Ω		DCL	Within initial limits				
			ESR	Within initia	Il limits			
	Extreme temperature exposure at a		+25°C	-55°C	+85°C	+105°C/+125°C		
Towns and we Otability	succession of continuous steps at	Δ C/C	IL*	±20%	±20%	±30%		
Temperature Stability	+25°C, -55°C, +25°C, +85°C,	DF	IL	IL	1.2 x IL	1.5 x IL		
	+105°C/+125°C***, +25°C	DCL	IL	n/a	10 x IL	10 x IL		
	AEO 0000 (AIII OTD 000 Markard 040 E)	O	Δ C/C	Within ±10	% of initial val	ue		
Machanical Charle()/ik	AEC-Q200 (MIL-STD-202, Method 213, Figure 1	DF	Within initial limits					
Mechanical Shock/Vibration	AEC-Q200 (MIL-STD-202, Method 204, 5 gs fo	r 20 min/12	ESR	Within initia	Within initial limits			
	cycles each of 3 orientations. Test from $10-2$,	000 Hz).	DCL	Within initia	ıl limits			

^{*} IL = Initial Limit

Certification

KEMET's Internal Qualification Plan for this tantalum series of capacitors follows AEC-Q200 guidelines. The humidity bias is limited to a maximum of 500 hours.

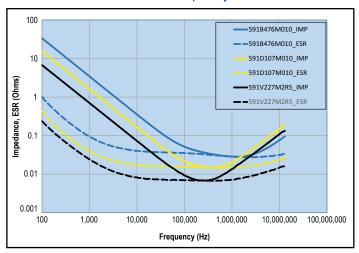
^{**} Minimum temperature test condition at 85°C

^{***} Refer to part number specifications for individual temperature classification

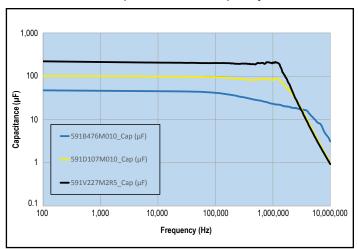


Electrical Characteristics

ESR vs. Frequency

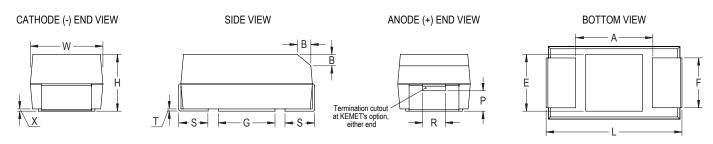


Capacitance vs. Frequency



Dimensions – Millimeters (Inches)

Metric will govern



Case	Size		Component											
KEMET	EIA	L*	W*	H*	F* ±0.1 ±(.004)	S* ±0.3 ±(.012)	B* ±0.15 (Ref) ±.006	X (Ref)	P (Ref)	R (Ref)	T (Ref)	A (Min)	G (Ref)	E (Ref)
В	3528-21	3.5 ±0.2 (0.138 ±0.008)	2.8 ±0.2 (0.110 ±0.008)	1.9 ±0.1 (0.075 ±0.004)	2.2 (0.087)	0.8 (0.031)	0.4 (0.016)	0.10 ±0.10 (0.004 ±0.004)	0.5 (0.020)	1.0 (0.039)	0.13 (0.005)	1.1 (0.043)	1.8 (0.071)	2.2 (0.087)
D	7343-31	7.3 ±0.3 (0.287 ±0.012)	4.3 ±0.3 (0.169 ±0.012)	2.8 ±0.3 (0.110 ±0.012)	2.4 (0.094)	1.3 (0.051)	0.5 (0.020)	0.10 ±0.10 (0.004 ±0.004)	0.9 (0.035)	1.0 (0.039)	0.13 (0.005)	3.8 (0.150)	3.5 (0.138)	3.5 (0.138)
V	7343-20	7.3 ±0.3 (0.287 ±0.012)	4.3 ±0.3 (0.169 ±0.012)	2.0 max (0.079)	2.4 (0.094)	1.3 (0.051)	n/a	0.05 (0.002)	n/a	n/a	0.13 (0.005)	3.8 (0.150)	3.5 (0.138)	3.5 (0.138)

Notes: (Ref) – Dimensions provided for reference only. No dimensions are provided for B, P or R because low profile cases do not have a bevel or a notch.

^{*} MIL-PRF-55365/8 specified dimensions



Table 1 – Ratings & Part Number Reference

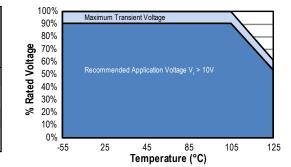
Rated Voltage	Rated Cap	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR	Maximum Allowable Ripple Current	MSL	Maximum Operating Temp
VDC @ 105°C	μF	KEMET/EIA	(See below for part options)	μΑ @+25°C Max/5 Min	% @ +25°C 120 Hz Max	mΩ @ +25°C 100 kHz Max	mA @ +45°C 100 kHz	Reflow Temp ≤ 260°C	°C
2.5	220	V/7343-20	T591V227M2R5ATE009	55.0	10	9	4558	3	105
6.3	33	B/3528-21	T591B336M006ATE080	20.8	8	80	1260	3	125
6.3	47	B/3528-21	T591B476M006ATE070	29.6	8	70	1347	3	125
10	33	B/3528-21	T591B336M010ATE080	33.0	8	80	1260	3	125
10	47	B/3528-21	T591B476M010ATE070	47.0	8	70	1347	3	125
10	100	D/7343-31	T591D107M010ATE025	100	10	25	3000	3	125

Refer to Ordering Information for additional detail.

Higher voltage ratings and tighter tolerance product including ESR may be substituted within the same size at KEMET's option. Voltage substitution will be marked with the higher voltage rating. Substitutions can include those better than the series.

Derating Guidelines

Voltage Rating	Maximum Recommended Steady State Voltage	Maximum Recommended Transient Voltage (1ms – 1µs)					
	-55°C to 105°C						
2.5 V ≤ V _R ≤ 10 V	90% of V _R	V _R					
	105°C to 125°C						
2.5 V ≤ V _R ≤ 10 V	60% of V _R	67% of V _R					



 V_R = Rated Voltage



Ripple Current/Ripple Voltage

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

- 1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.
- The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

	Temperature Compensation Multipliers for Maximum Ripple Current							
I	T ≤ 45°C							
ı	1.00 0.90 0.40 0.25							

T= Environmental Temperature

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

 $I(max) = \sqrt{P \max/R}$ $E(max) = Z \sqrt{P \max/R}$

I = rms ripple current (amperes) E = rms ripple voltage (volts) R = ESR at specified frequency (ohms) Z = Impedance at specified frequency (ohms)

P max = maximum power dissipation (watts)

Reverse Voltage

Polymer tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected in the wrong polarity. These devices will withstand a small degree of transient voltage reversal for short periods as shown in the below table.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
55°C	10% of Rated Voltage
85°C	5% of Rated Voltage
105°C	3% of Rated Voltage
125°C*	1% of Rated Voltage

^{*}For series rated to 125°C

Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts @ 45°C with +30°C Rise
В	3528-21	127
D	7343-31	225
V	7343-20	187

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.

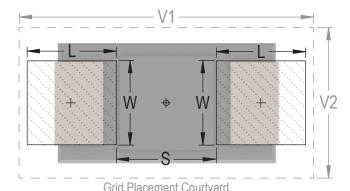


Table 2 – Land Dimensions/Courtyard

KEMET	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)			Density Level B: Median (Nominal) Land Protrusion (mm)			Density Level C: Minimum (Least) Land Protrusion (mm)								
Case	EIA	W	L	S	V1	V2	W	L	S	V1	V2	W	L	S	V1	V2
В	3528–21	2.35	2.21	0.92	6.32	4.00	2.23	1.80	1.12	5.22	3.50	2.13	1.42	1.28	4.36	3.24
D	7343–31	2.55	2.77	3.67	10.22	5.60	2.43	2.37	3.87	9.12	5.10	2.33	1.99	4.03	8.26	4.84
V	7343–20	2.55	2.77	3.67	10.22	5.60	2.43	2.37	3.87	9.12	5.10	2.33	1.99	4.03	8.26	4.84

Density Level A: For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. **Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component desity product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC standard 7351 (IPC-7351).

² Land pattern geometry is too small for silkscreen outline.



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¹ Height of these chips may create problems in wave soldering.



Soldering Process

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Please note that although the X/7343–43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

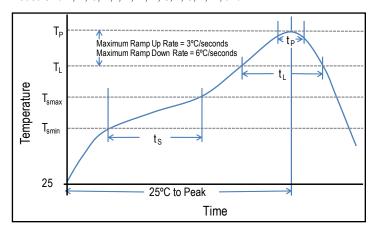
During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Minimum (T _{Smin})	100°C	150°C
Temperature Maximum (T _{Smax})	150°C	200°C
Time (t_s) from T_{smin} to T_{smax})	60 – 120 seconds	60 – 120 seconds
Ramp-up Rate (T _L to T _P)	3°C/seconds maximum	3°C/seconds maximum
Liquidous Temperature (T _L)	183°C	217°C
Time Above Liquidous (t _L)	60 – 150 seconds	60 – 150 seconds
Peak Temperature (T _P)	220°C* 235°C**	250°C* 260°C**
Time within 5°C of Maximum Peak Temperature (t _p)	20 seconds maximum	30 seconds maximum
Ramp-down Rate $(T_p \text{ to } T_L)$	6°C/seconds maximum	6°C/seconds maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

*Case Size D, E, P, Y, and X

**Case Size A. B. C. H. I. K. M. R. S. T. U. V. W. and Z

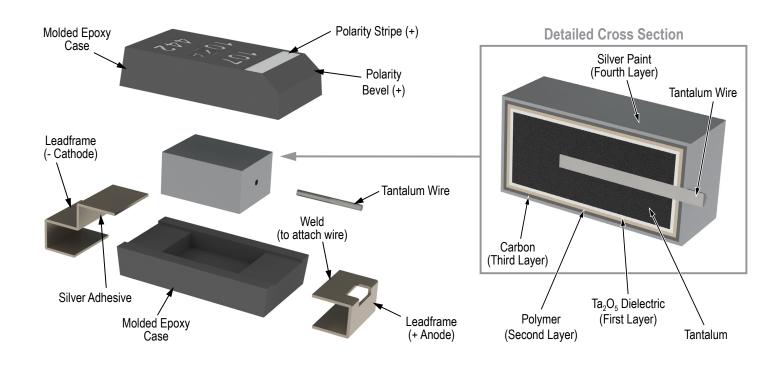


Storage

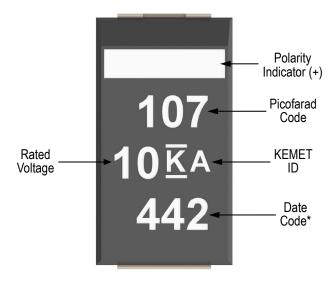
All KO-CAP series are shipped in moisture barrier bags with a desiccant and moisture indicator card. These series are classified as MSL3 (Moisture Sensitivity Level 3). Product contained within the moisture barrier bags should be stored in normal working environments with temperatures not to exceed 40°C and humidity not in excess of 60% RH.



Construction



Capacitor Marking



 $*442 = 42^{nd}$ week of 2014

Date Code *						
1st digit = Last number of Year	4 = 2014 5 = 2015 6 = 2016					
2 nd and 3 rd digit = Week of the Year	01 = 1st week of the Year to 52 = 52nd week of the Year					



Tape & Reel Packaging Information

KEMET's molded tantalum and aluminum chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481*: Embossed Carrier Taping of Surface Mount Components for Automatic Handling. This packaging system is compatible with all tape-fed automatic pick-and-place systems.

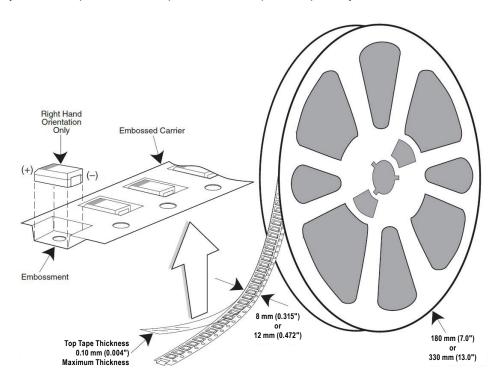


Table 3 - Packaging Quantity

Case Code		Tape Width (mm)	7" Reel*	13" Reel*	
KEMET	EIA				
S	3216-12	8	2,500	10,000	
Т	3528-12	8	2,500	10,000	
М	3528-15	8	2,000	8,000	
U	6032-15	12	1,000	5,000	
L	6032-19	12	1,000	5,000	
W	7343-15	12	1,000	3,000	
Z	7343-17	12	1,000	3,000	
V	7343-20	12	1,000	3,000	
Α	3216-18	8	2,000	9,000	
В	3528-21	8	2,000	8,000	
С	6032-28	12	500	3,000	
D	7343-31	12	500	2,500	
Q	7343-12	12	1,000	3,000	
Υ	7343-40	12	12 500		
Х	7343-43	12	500	2,000	
E/T428P	7360-38	12	500	2,000	
Н	7360-20	12	1,000	2,500	

^{*} No C-Spec required for 7" reel packaging. C-7280 required for 13" reel packaging.



Figure 1 – Embossed (Plastic) Carrier Tape Dimensions

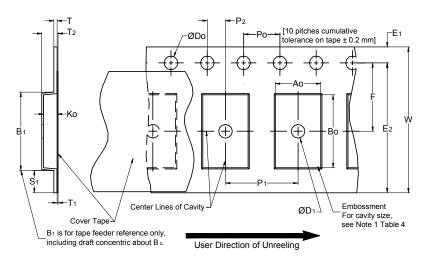


Table 4 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D ₀	D ₁ Minimum Note 1	E ₁	P ₀	P ₂	R Reference Note 2	S ₁ Minimum Note 3	T Maximum	T ₁ Maximum
8 mm		1.0 (0.039)			2.0 ±0.05	25.0 (0.984)			
12 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.5	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	(0.079 ±0.002)	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm	(3.2.2.2.2.00 // 0.0)	(0.059)	(31232 20100 1)	(3.1.3. 20.00 1)	2.0 ±0.1 (0.079 ±0.059)	(1.181)	(3:32:)	(3:32:)	

Variable Dimensions — Millimeters (Inches)								
Tape Size	Pitch	B ₁ Maximum Note 4	E ₂ Minimum	F	P ₁	T ₂ Maximum	W Maximum	A ₀ , B ₀ & K ₀
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	2.0 ±0.05 or 4.0 ±0.10 (0.079 ±0.002 or 0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	2.0 ±0.05 (0.079 ±0.002) or 4.0 ±0.10 (0.157 ±0.004) or 8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)	Note 5
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5±0.10 (0.295 ±0.004)	4.0 ±0.10 (0.157 ±0.004) to 12.0 ±0.10 (0.472 ±0.004)	8.0 (0.315)	16.3 (0.642)	

- The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
- 2. The tape, with or without components, shall pass around R without damage (see Figure 4).
- 3. If S₁ < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).
- 4. B₁ dimension is a reference dimension for tape feeder clearance only.
- 5. The cavity defined by A_o , B_o and K_o shall surround the component with sufficient clearance that:
 - (a) the component does not protrude above the top surface of the carrier tape.
 - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
 - (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).
 - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).
 - (e) see Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.



Packaging Information Performance Notes

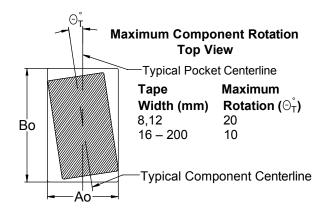
- 1. Cover Tape Break Force: 1.0 Kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength		
8 mm	0.1 to 1.0 Newton (10 to 100 gf)		
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)		

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165 $^{\circ}$ to 180 $^{\circ}$ from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 \pm 10 mm/minute.

3. Labeling: Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624.*

Figure 2 – Maximum Component Rotation



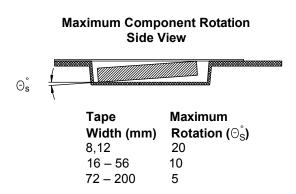


Figure 3 – Maximum Lateral Movement

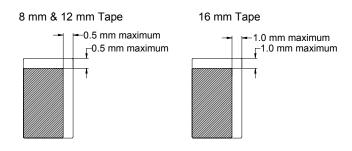


Figure 4 – Bending Radius

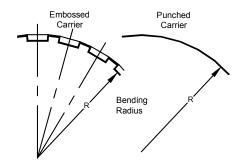
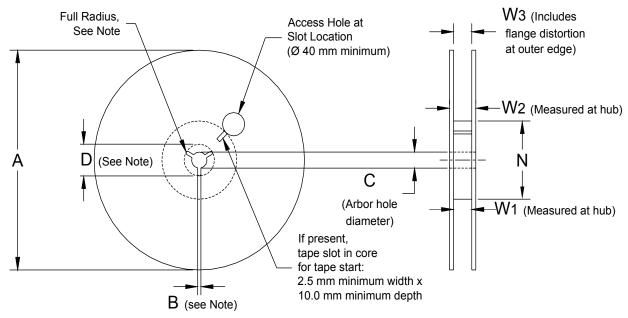




Figure 5 – Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 5 - Reel Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)								
Tape Size	A	B Minimum	С	D Minimum				
8 mm	178 ±0.20 (7.008 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)				
12 mm	or							
16 mm	330 ±0.20 (13.000 ±0.008)							
	Variable Dimensions — Millimeters (Inches)							
Tape Size	N Minimum	W ₁	W ₂ Maximum	W ₃				
8 mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)					
12 mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference				
16 mm	(1.303)	16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	without interreterioe				



Figure 6 – Tape Leader & Trailer Dimensions

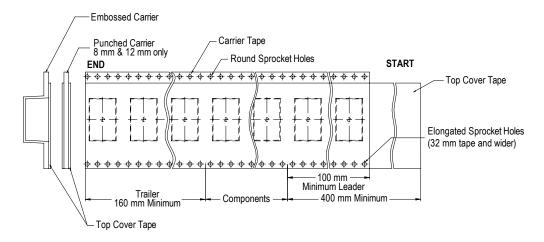
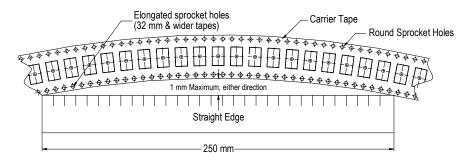


Figure 7 – Maximum Camber





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